

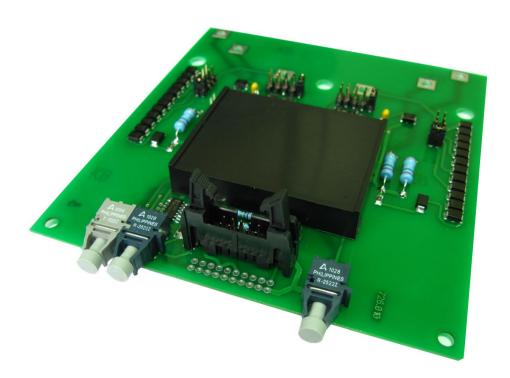
ELECTRUM AV

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TRANSISTOR IGBT AND MOSFET DRIVER DR2180P–BF ANALOGUE OF 2SB315B

USER'S MANUAL



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CONTENTS

1 OVERVIEW	3
2 DRIVER COMPOSITIONS	
3 FUNCTIONAL DRIVER FEATURES	
4 BASIC AND MAXIMUM PERMISSIBLE PARAMETERS	5
5 DRIVER OPERATION	6
6 DRIVER CONNECTION RECOMENDATIONS	7
7 DRIVER ADJUSTMENT RECOMMENDATIONS	
8 GRAPHS EXPLAINING DRIVER OPERATION	9
9 INFORMATION ABOUT PRECIOUS METALS	10
10 SERVICE RECOMMENDATIONS	10
11 RELIABILITY SPECIFICATIONS	11

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1 OVERVIEW

A double-channel driver of powerful transistors with field drive (MOSFET or IGBT) (hereinafter – driver) is intended for dependant galvanic isolated controlling of two power transistors with maximum permissible voltage up to 3300 V. The driver is an amplifier – generator of transistor gates control signals with frequency up to 100 kHz. The driver contains built-in galvanic isolated DC/DC-converter, providing requisite levels of unlocking and locking voltages on transistor gate. The driver is an analogue of **2SB315B** in structure and function.

2 DRIVER COMPOSITIONS

2.1 The driver is a printed-circuit board with mounted driver module on it (DM), made in a hermetic plastic housing, necessary tuning element and connectors for connection of controlled transistors and control signals.

2.2 The driver contains the following functional assemblies:

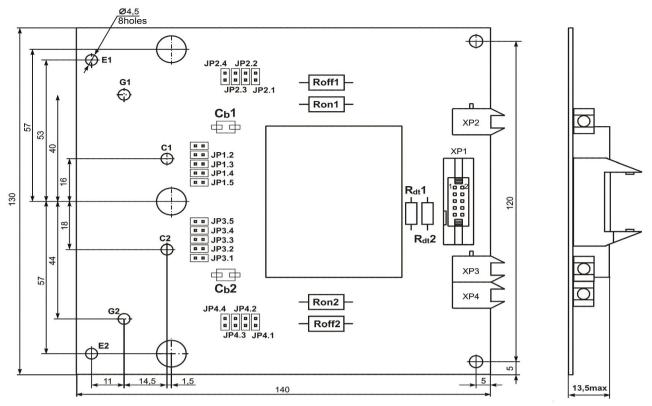
- 1 Driver supply voltage stabilizer with protection against false turn-on polarity;
- 2 Built-in DC-DC converter with stabilization of unlocking and locking voltage levels on gates of controlled transistors;
- 3 Input logics;
- 4 Drive circuit of controlled transistor gates;
- 5 Protection circuit against under-voltage and overvoltage on controlled transistors gate;
- 6 Protection circuit of controlled transistors against current overload.

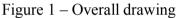
3 FUNCTIONAL DRIVER FEATURES

3.1 The driver provides the following drive functions, control and protection functions of controlled transistor:

- 1 Collector saturation voltage control of controlled transistor, its protective disconnection when saturation state output;
- 2 Protective turn-off threshold regulation on saturation voltage;
- 3 Soft driver junction from active state to inactive one when an "emergency" (output of controlled transistor from saturation mode);
- 4 Control block when an "Emergency";
- 5 Emergency alarm;
- 6 On/off time regulation of controlled transistor by means of change of resistor resistance in output circuit (Ron, Roff);
- 7 Block of simultaneous turn-on of upper and lower arm;
- 8 Switching delay of upper and lower arm;
- 9 Switching delay regulation of upper and lower arm;
- 10 Driver supply voltage control (built-in comparators) on DC/DC converter output.

3.2 Overall drawing is shown at Figure 1, functional driver scheme is represented at Figure 2.





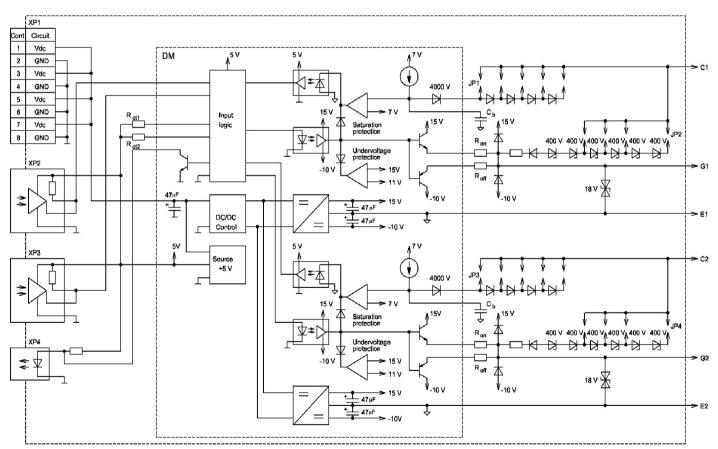


Figure 2- Functional driver circuit

XP1 – IDCC-10MS plug; mate – socket IDC-10 XP2, XP3 – HFBR-2522 signal receiver XP4 –HFBR-1522 signal transmitter

3.3 Output function is given in Table 1.

Output No.	Symbol	Function
1	Vdc	Supply +15 V
2	GND	Ground of supply- and control circuits
3	Vdc	Supply +15 V
4	GND	Ground of supply- and control circuits
5	Vdc	Supply +15 V
6	GND	Ground of supply- and control circuits
7	Vdc	Supply +15 V
8	GND	Ground of supply- and control circuits
9	-	Not involved
10	-	Not involved

Table 1 – Output function of XP1

4 BASIC AND MAXIMUM PERMISSIBLE PARAMETERS

Parameter	Symbol	Unit	Value			Note
Faranieter	5		min	type	max	Note
DC/DC block characteristic						
Supply voltage	U_S	V	13.5	15	16.5	
Off-load current consumption	Is	mA		100	120	$F_{cont} = 0 Hz$
Maximum current consumption	I _{S max}	mA			550	Under load ref. to Figure 5 and 6
Power of built-in power supply of output part	P _{DC-DC}	W	3			For each channel
	Voltage moni	tor characte	eristics			
Protection turn-on threshold	U _{UVLO-}	V		11		DC DC autrait
Protection turn-off threshold	U _{UVLO+}	V		12		DC-DC output
	Control inp	ut character	ristics			
Wave length, used when signal transmission and receiving	λ	nm		660		
	Time ch	aracteristic	S			
Turn-on/off delay time input-output	td (in-out)	μs			0.5	Ref. to Figure 11
«Dead time» between signal changes of the first and second output channel	t _{TD}	μs	2			Set by consumer; ref. to Figure 10
Maximum operating frequency	f_{\max}	kHz			100	No-load; ref. to Figure 5 and 6
Non-saturation protection operation delay time	t _{BLOCK1}	μs	2			Set by consumer; ref. to Figure 9
Lock time of controlled transistor after "Emergency"	t _{BLOCK2}	ms		70		
Soft emergency shutdown time of controlled transistor	toff	μs		1.5		
Emergency turn-on delay time	td _(on-err)	μs			2	
Output characteristics						
High level output voltage	U _{OH}	V	+12	+15	+18	In all range of
Low level output voltage	U _{OL}	V	-8	-10	-12	permissible loads
Maximum output pulse on current	I _{Omax on}	А	+18	20		ref. to Figure 8
Maximum output pulse off current	I _{Omax off}	А		-22	-18	ici. to riguie o

A yora go output ourront	T	100 Å			130	To each channel
Average output current	Io	mA				
Rise and fall time of output signal	t _{r (f)}	ns			150	ref. to Figure 11
Saturation voltage that corresponds	Th					Set by consumer;
to non-saturation protection	U_{MC}^{III}	V			5.0	ref. to Table 3
operation	- 1110					
Length of status signal transmission	L _{err}	m	25			
	Insulation	characteris	tics			
Maximum permissible reverse col-	ΤT	V			4000	
lector voltage	U_{C}	v			4000	
Insulation voltage between input	T	X 7			7500	
and output	U _{ISO(IN-OUT)}	V			7500	DC, 1 minute
Insulation voltage between output of	U _{ISO(OUT1-}	X Z			4000	
the first and second channel	OUT2)	V			4000	DC, 1minute
Critical rate of output voltage					20	
change	$(dU/dt)_{cr}$	kW/ μs			20	
Prote	ction character	ristics agains	st overvo	ltage		·
Protection operation voltage against				800		JP2(4).1 installed
collector-emitter overvoltage of	T T	* 7		1200		JP2(4).2 installed
controlled transistor (ref. to figure	U_{AC}	V		1600		JP2(4).3 installed
12)				2400		JP2(4).4 installed
Characteristics of controlled transistor						
Maximum permissible voltage of					2200	
controlled transistor	U_{CE} (U_{DS})	V			3300	
Service and storage characteristics						
Operating temperature range	T _A	°C	-45		+85	
Storing temperature	Ts	°C	-60		+100	

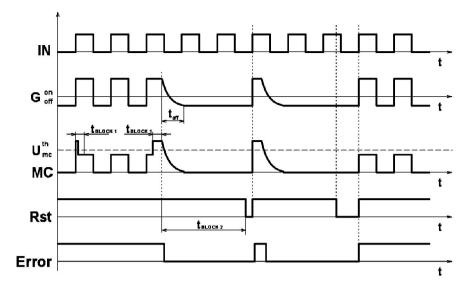
5 DRIVER OPERATION

Delivery of light pulse to the receiver of control signal XP2 and will XP3 lead to opening of controlled transistor. Open state voltage fall increasing by more than U_{mc}^{Th} per time, exceeding t_{BLOCK1} , will lead to protection operation of open state voltage fall increasing (current overload). When "emergency" the LED of XP4 receiver will not light. In 70 ms emergency reset will be performed by internal circuit of emergency reset and on rising edge of control signal «IN» the controlled transistor will be opened. In the case when the emergency cause was not disposed then the protection cycle will be recurred.

Driver supply voltage decrease that leads to output voltage reduction to protection operation threshold level against driver supply undervoltage « U_{uvlo-} » will entail closing of controlled transistor regardless of input control signals. Control signals will recover if supply voltage is increased to value that provides output voltage on protection operation threshold level against driver supply undervoltage « U_{uvlo+} ». There is not an error signal on XP4 transmitter when protection operation against supply undervoltage.

The simultaneous delivery of light pulses to receivers of control signal XP2 and XP3 will lead to control block and controlled transistors will be closed (simultaneous turn-on block), thereby error signaling will not arise.

Diagrams explaining driver operation is shown at Figures 3 and 4.



Rst - Periodical internal signal of "emergency" reset

Figure 3 - Functional diagram of driver operation at «emergency»

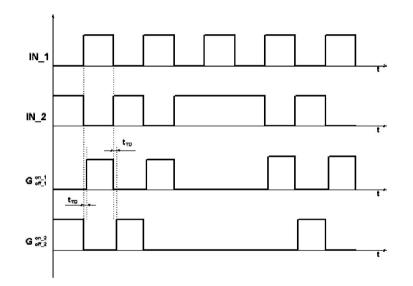


Figure 4 – Functional diagram of driver operation

6 DRIVER CONNECTION RECOMENDATIONS

XP2, XP3 receivers of controlled signal. It is a converter microcircuit of light pulses to logic control signals. The wave length that is used when signal's transmission and reception is 660 ns.

XP4 status transmitter. It is a microchip for light signal forming about driver operation mode. In case of normal driver operation there is a light signal on transmitter output. The transmitter is disconnected only when emergency caused by current overload of power transistor; if driver supply voltage is decreased to $(U_{uv})_{uv}$ then the transistors will be closed regardless of input control signals (the signals will be recovered when supply level reaching corresponding $(Uuv)_{uv}$), but there will be no error signaling in this case.

Vdc – driver supply connector. You should note that when driver supply voltage decreases, the output voltage of DC/DC – converter will be also decreased. Therewith if the supply is lower than the permissible level the input circuit can operate regularly, but the voltage on gates of controlled transistor can drop to level «U_{uv}lo-» and transistor control will be false.

Maximum no-load current consumption on supply input is 120 mA. When transistors connection the current consumption will increase by value of gate recharge current and can reach 550 mA equal to the both channels). At higher current consumption DC/DC – converter can fail, or, on short-time current consumption increasing by 550 mA, output voltage of DC/DC – converter will decrease to unallowable level and undervol-

tage protection will operate, that will lead to faulty transistor drive. If the channel load is assigned irregularly then current consumption by one channel should not exceed 250 mA. Current consumption depends on control signal frequency, gate capacitance and gate resistors values as well as on input gate capacitance (ref. to Figure 6). Thereby, when using the driver you must make a correction for current consumption subject to transistors, which the driver will work on. Safe operation area of the driver versus gate capacitance and frequency is shown at Figure 5.

GND – ground of control- and supply circuits; thereby control circuit does not have a galvanic isolation with DC/DC-converter input.

Resistors Rdt1, **Rdt2** –timing resistor of switching delay setting of the first and second channel. Actually resistors regulate turn-on delay time thereby when you install the resistors with different nominal the rise time switching delay of controlled pulses of the first and second channel will be different. If there is no need to increase of switching delay time then you should install the jumpers instead of resistors. The dependence of delay time on resistor nominal is shown at Figure 10. Initially resistors of nominal 1 Ω are installed that corresponds to min. "dead time" (2 µs).

Capacitors C_{b1} , C_{b2} – timing capacitors of turn-on delay of corresponding controlled transistor at current overload. Protection operation delay is necessary to avoid maloperation of short-time inductive kicks and of transient process when turn-on. Thereby when emergency the delay time will be equal to "rerun pulse" time.

In order to increase protection operation delay it is recommended to install the capacitor with nominal shown at Figure 9. Initially capacitor of 100 pF is installed that corresponds to delay time 5 μ s (typ.).

G1, G2 – outputs for gates connection of controlled transistors.

Gate resistors (Ron1, Ron2, Roff1 and Roff2) are necessary for maximum pulse current decrease. Resistor installing with every nominal is allowed, including 0 Ω . Resistor installing with different nominal is also allowed; for instance, in order to increase turn-on time of controlled transistor purposely to decrease voltage amplitude of inductive kicks. Output pulse current versus gate resistor nominal is shown at Figure 8.

Initially the resistors of 0.2 Ω are installed that corresponds to maximum pulse current.

C1, C2 – collector (drain) connection output of controlled transistor. The outputs are intended for voltage fall controlling (saturation protection) on collector-emitter transistor. The maximum value of protection operation threshold is 5.0 V. Protection operation threshold is regulated by JP1, JP3 position. If there is no need any protection against overload current of controlled transistor then «C» output should be short-circuited to emitter output of the corresponding channel.

E1, E2 – emitter connection outputs of controlled transistor.

Jumpers

JP1, JP3 – jumpers that regulate non-saturation protection operation threshold of controlled transistor. Protection operation voltage versus the installed jumper is shown in Table 3. If none of the jumpers are installed then the driver is in an emergency mode.

Jumper of channel 1	Jumper of channel 2	Protection threshold, V (typ.)
JP1.1	JP3.1	3.0
JP1.2	JP3.2	3.5
JP1.3	JP3.3	4.0
JP1.4	JP3.4	4.5
JP1.5	JP3.5	5.0

Table 3 – Non-saturation protection threshold versus the installed jumper.

JP2, JP4 – jumpers that connect protection against collector-emitter overvoltage of controlled transistor of channel 1 and 2 accordingly. Thereby voltage operation 800 V corresponds to JP2 (4).1 position, 1200 V corresponds to JP2 (4).2 position, 1600 V corresponds to JP2 (4).3 position, 2400 V corresponds to JP2(4).4 position.

7 DRIVER ADJUSTMENT RECOMMENDATIONS

In order to create the driver that is an analogue to the plug-n-play 2SB315B the special module it is recommended to adjust the DR2180P-BF driver in compliance with 2SB315B Driver. You should adhere to the following technique when the driver setting up: 1. Disconnect 2SB315B driver from the module, connect DC voltage sources between collector and emitter outputs, control gate signal.

2. Signal and measure switching "dead time" (level 0V);

3. Measure protection operation voltage by smooth rising of voltage at the sources that imitate transistor saturation voltage;

4. Relative to protection operation threshold you should increase the voltage twice and measure desaturation protection operation delay

5. Reset "Emergency" mode, set up the frequency of control signal 0.1...1 kHz, connect RC-chain (resistor to gate) between gate and emitter with nominal 0.1 $\Omega/1\mu$ F (non-polar condenser). Connect the driver and measure resistor voltage drop (measurement of pulse driver current).

6. Set up DR2180P-BF in compliance with the characteristics of 2SB315B driver, notably:

- set up "dead" time by Rdt resistor in accordance with the Figure 10;

- set up non-saturation protection operation voltage by JP1, JP3 in accordance with Table 3;

- set up protection operate delay time by capacitor Cb in compliance with Figure 9;

- set up output pulse current by resistor Rg on(off) in compliance with Figure 8.

7. Measure the received parameter of DR2180P-BF similarly to 2SB315B driver test, be assured in their equivalent.

8. Connect the driver to the power module and be sure that the converter operates by analogy to the variant of 2SB315B driver.

8 GRAPHS EXPLAINING DRIVER OPERATION

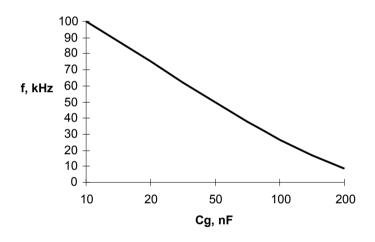


Figure 5 – Safe operation area versus frequency and gate capacitance (with gate resistor 1 Ω)

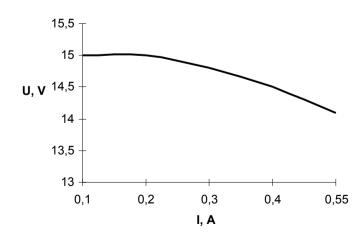


Figure 7 – Transistor gate voltage versus current consumption

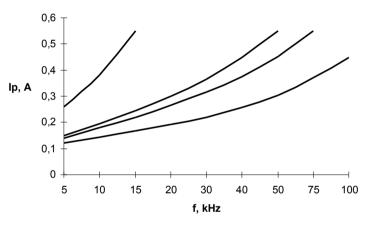


 Figure 6 – Current consumption versus signal frequency under load (with gate resistor 1 Ω)
For gate capacitance 10 nF, 25 nF, 50 nF, 100 nF

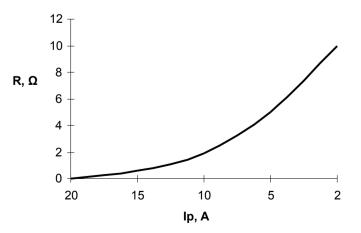
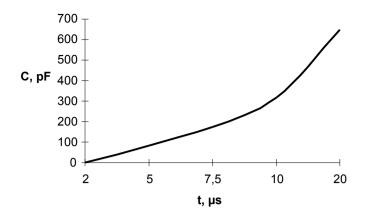
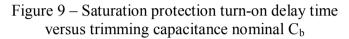


Figure 8 – Output pulse current versus gate resistor nominal





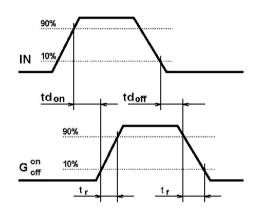


Figure 11 – Diagram explaining timing driver characteristics where IN – input control signal; G – gate signal of controlled transistor

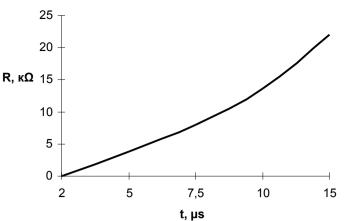


Figure 10 – "Dead time" duration versus trimming resistor nominal R_{dt}

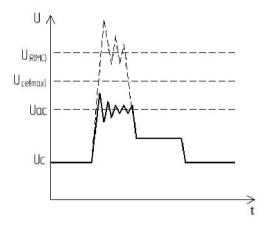


Figure 12 – Driver operation when collector-emitter overvoltage protection of controlled transistor operates where Uac – protection operate voltage against overvoltage; Uce(max) – max. collector-emitter voltage of power transistor, Ur(mc) – max. reverse voltage on collector output

9 INFORMATION ABOUT PRECIOUS METALS

Precious metals are not contained.

10 SERVICE RECOMMENDATIONS

10.1 Resistance requirements at mechanical impacts

Mechanical impacts for drivers in accordance with qualifying standards of controlled power transistors are shown in Table 4.

Table 4 – Drivers resistance requirements to mechanical impact factors

External exposure factors	External exposure factor value
Sinusoidal vibration:	
- frequency range, Hz;	0.5 - 100
- acceleration amplitude, m/s^2 (g)	150 (15)
Mechanical shock of single action:	
- peak shock acceleration, m/s^2 (g);	40 (4)
- pulse duration of shock acceleration, ms	50

10.2 Resistance requirements at climatic impacts

Table 5 - Resistance requirements to climatic impact factors	
Climatic factor	Climatic factor value
Lower ambient temperature:	
- operating, °C;	minus 45
- maximum, °C	minus 60
Higher ambient temperature:	
- operating, °C;	+85
- maximum, °C	+100
Relative humidity with temperature 35 °C without	
moisture condensation, %, max	98
Ambient temperature change, °C	from minus 60 to +100
Lower atmospheric pressure, Pa (mm Hg)	86000 (650)
Higher atmospheric pressure, Pa (mm Hg)	106000 (800)

11 RELIABILITY SPECIFICATIONS

The manufacturer guarantees the quality of the module all the requirements of the user's manual if the consumer observes terms and conditions of storage, mounting and operation, as well as guidance on the application specified in the user's manual.

Operating warranty is 2 years from the acceptance date, in the case of regualification – from the date of the requalification.

Reliability probability of the driver for 25000 hours must be at least 0.95.

Gamma-percent life must be not less than 50000 hours by $\gamma = 90$ %.

Gamma-percent service life of the modules, subject to cumulative operating time is not more than gammapercent life, not less than 10 years, at $\gamma = 90$ %.

Gamma-percent storageability time of the modules, at $\gamma = 90$ % and storing – 10 years.

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